

(b) a silicide layer bonded by said first bonding material to said first dielectric layer;

(c) a device wafer comprising a device layer and a second dielectric layer comprising a [a] second bonding material, said second dielectric layer being bonded to said silicide_layer and said device layer by said second bonding material; and

(d) interconnected transistors in and at a surface of said device layer;

wherein said silicide layer [comprises] is bonded by a third bonding material [that bonds said silicide layer] to said handle die and said device wafer.

Further amend claim 11 as follows:

not OK
11. (Twice amended) The integrated circuit of claim [10] 15 wherein said device layer is silicon and includes doped buried layers abutting said [silicide] diamond layer and forming components of said transistors.

Further amend claim 13 as follows:

not OK
13. (Twice amended) The integrated circuit of claim 10 wherein said handle die is silicon and said first dielectric layer is [silicon dioxide] [portion adjacent said homogeneous silicide layer].

Remarks

Claims 4 and 5 are amended to depend on claim 7 and to more clearly define the dielectric layers. These amendments are supported by FIG. 4(a) and by the specification at page 7, lines 22-29.

Claim 10 is further amended to remove an extraneous "a" from line 7 and to clarify the operation of the third binding material to bind the silicide layer to the handle die and the device wafer.

Claim 11 is further amended to depend on claim 15 and to recite that the buried layers abut the diamond layer. This amendment is fully supported by FIG. 6 and page 11, lines 2-16, of the specification.

Claim 13 is further amended by inserting an open bracket before "portion." This bracket was inadvertently omitted in the previously filed amendment of claim 13.

The instant application, filed May 21, 1999, has again been objected to under U.S.C. § 132 on the grounds that it introduces new matter that is not supported by the disclosure of the original parent application. Relatedly, claims 1-5, 7-11, and 13-22 have been finally rejected